



Material Content Data Sheet



Sales Product Name	TLE42694G			Issued	25. September 2017			
MA#	MA000970066							
Package	PG-DSO-8-16			Weight*	83.30 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.391	2.87	2.87	28701	28701
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8609	
wire	non noble metal	copper	7440-50-8	29.121	34.96	35.87	349575	358722
	noble metal	gold	7440-57-5	0.167	0.20	0.20	2010	2010
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.12		1156
encapsulation	plastics	epoxy resin	-	4.428	5.32		53156	
	inorganic material	silicondioxide	60676-86-0	43.608	52.34	57.78	523474	577786
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9769	9769
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7806	7806
glue	plastics	acrylic resin	-	0.279	0.33		3345	
	noble metal	silver	7440-22-4	0.988	1.19	1.52	11861	15206
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com